

## CLAIMS

1. A thermal dissipating element of a chip,  
comprising:

- 5       a cover including a top plate and a side plate, said  
top plate curving and extendedly connecting to be said  
side plate, wherein said top plate has a top surface and a  
bottom surface; and
- 10       a lump including a top face, a bottom face and a side,  
wherein said lump is fastened inside said cover, and said  
top face contacts with said bottom surface.

2. The thermal dissipating element according to  
claim 1, wherein said bottom face contacts with said chip.  
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3. The thermal dissipating element according to  
claim 1, wherein the shape of said bottom face is circular.

4. The thermal dissipating element according to  
20 claim 1, wherein the shape of said bottom face is  
quadrilateral.

5. The thermal dissipating element according to

claim 1, wherein said top face is fastened on said bottom surface by an adhesive.

6. The thermal dissipating element according to  
5 claim 1, wherein the shape of said top face is circular.

7. The thermal dissipating element according to claim 1, wherein the shape of said top face is quadrilateral.

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8. The thermal dissipating element according to claim 1, wherein said side contacts with said side plate.

9. The thermal dissipating element according to  
15 claim 1, wherein said lump is a silicon chip.

10. The thermal dissipating element according to claim 1, further comprising a sole plate to extendedly connect to said side plate.

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11. The thermal dissipating element according to claim 10, said side plate and said sole plate including a plurality of holes, said holes being formed between said side plate and said sole plate.

12. The thermal dissipating element according to claim 10, wherein said sole plate includes a plurality of cavities.

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13. The thermal dissipating element according to claim 1, wherein the material of said lump is metal.

14. The thermal dissipating element according to  
10 claim 13, wherein the material of said lump is aluminum.

15. The thermal dissipating element according to claim 13, wherein the material of said lump is copper.

15 16. A chip packaging element, comprising :

a substrate ;

a chip fastened on said substrate ; and

a thermal dissipating element of said chip, said  
thermal dissipating element including a top plate, a side  
20 plate, a sole plate and a lump, said top plate curving and  
extendedly connecting to be the side plate, said side plate  
curving and extendedly connecting to be the sole plate,  
said lump fastened on said top plate, wherein said sole  
plate is fastened on said substrate, said lump contacts

with said chip, and said chip is fastened on said lump and said substrate.

17. The chip packaging element according to claim  
5 16, wherein said lump is fastened on said top plate by an adhesive with high thermal conductivity.

18. The chip packaging element according to claim  
16, wherein said lump contacts with a portion of said side  
10 plate.

19. The chip packaging element according to claim  
16, said lump comprising a top surface and a bottom  
surface being opposite to each other, wherein said lump is  
15 fastened on a portion of said bottom surface.

20. The chip packaging element according to claim  
16, said lump comprising a top surface and a bottom  
surface being opposite to each other, wherein said lump is  
20 fastened on all of said bottom surface.